



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10B472KB8NNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 4.7 nF, 50V, ±10%, X7R, 0603

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>B</u> <u>472</u> <u>K</u> <u>B</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ 8 ⑨ ⑩ ⑪

① S	Series	Samsung Multi-layer Ceramic Capacitor							
② S	Size	0603 (inch c	ode)	L: 1.	6 ± 0.1	mm	W:	0.8 ± 0.1	mm
3 0	Dielectric	X7R		8	Inner e	electrode	N	li	
4 C	Capacitance	4.7 nF			Termin	ation	C	u	
⑤ C	Capacitance	±10 %			Plating	I	S	n 100%	(Pb Free)
to	olerance			9	Produc	et	N	lormal	
6 R	Rated Voltage	50 V		10	Specia	I	R	eserved for	future use
7 T	hickness	0.8 ± 0.1	mm	11	Packag	ging	C	ardboard T	ype,7"reel(4,000ea)

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1kHz±10% 1.0±0.2Vrms					
Tan δ (DF)	0.025 max.						
Insulation	More than 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance							
Appearance	No abnormal exterior appearance	Visual inspection					
Withstanding	No dielectric breakdown or	250% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	X7R						
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±15%)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120 ℃ for 10~30sec.)					
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5°C, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.	TOOLGET POL. 27010 0, 1011366.					

	Performance	Test condition				
Vibration Test	Capacitance change: within ±5%	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)				
		2hours × 3 direction (x, y, z)				
Moisture	Capacitance change: within ±12.5%	With rated voltage				
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0 hour				
	IR : More than 25MΩ· <i>μ</i> F					
High Temperature	Capacitance change: within ±12.5%	With 200% of the rated voltage				
Resistance	Tan δ : 0.05 max	Max. operating temperature				
	IR : More than 50MΩ·μF					
		1000+48/-0 hour				
Temperature	Capacitance change: within ±7.5%	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C				
		→ Max. operating temperature → 25°C				
		5 cycles test				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C , 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.